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April 2012

FDMC7582

N-Channel PowerTrench® MOSFET 25 V, 49 A, 5.0 m Ω

Features

- Max $r_{DS(on)}$ = 5.0 m Ω at V_{GS} = 10 V, I_D = 16.7 A
- Max $r_{DS(on)}$ = 7.5 m Ω at V_{GS} = 4.5 V, I_D = 13.6 A
- State-of-the-art switching performance
- Lower output capacitance, gate resistance, and gate charge boost efficiency
- Shielded gate technology reduces switch node ringing and increases immunity to EMI and cross conduction
- Clip bonding technology further reduces On resistance and source inductance
- RoHS Compliant

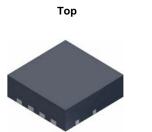


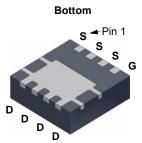
General Description

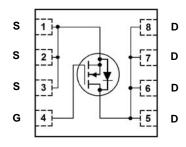
This N-Channel MOSFET has been designed specifically to improve the overall efficiency and to minimize switch node ringing of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low rds(on), fast switching speed and body diode reverse recovery performance..

Application

- High side switching for high end computing
- High power density DC-DC synchronous buck
- Low loss load switch
- Communication & telecon Point of Load







Power 33

MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V_{DS}	Drain to Source Voltage		25	V
V _{GS}	Gate to Source Voltage	(Note 3)	±20	V
	Drain Current - Continuous (Package limited) Tc=2	25C	49	
I_D	- Continuous (Silicon Limited) Tc=2	5C	76	^
	- Continuous T _A = 2	25 °C (Note 1a)	16.7	Α
	- Pulsed		60	
E _{AS}	Single Pulse Avalanche Energy	(Note 4)	38	mJ
D	Power Dissipation $T_C =$	25 °C	52	w
P_{D}	Power Dissipation $T_A =$	25 °C (Note 1a)	2.3	VV
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC7582	FDMC7582	Power 33	13 "	13 " 12 mm	

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	lest Conditions	IVIIN	тур	wax	Units
Off Chara	acteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250 μA , V_{GS} = 0 V	25			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA , referenced to 25 °C		19		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 20 V, V _{GS} = 0 V			1	μА
I_{GSS}	Gate to Source Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.2	1.7	2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μA , referenced to 25 °C		-5		mV/°C
		V _{GS} = 10 V, I _D = 16.7 A		4.0	5.0	
r _{DS(on)}	r _{DS(on)} Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 13.6 \text{ A}$		6.0	7.5	mΩ
	$V_{GS} = 10 \text{ V}, I_D = 16.7 \text{ A}, T_J = 125 ^{\circ}\text{C}$		5.4	7.0		
9 _{FS}	Forward Transconductance	$V_{DD} = 5 \text{ V}, I_D = 16.7 \text{ A}$		58		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 42 V V - 0 V		1348	1795	pF
Coss	Output Capacitance	V _{DS} = 13 V, V _{GS} = 0 V, f = 1 MHz		372	495	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 WILL		79	120	pF
R_g	Gate Resistance		0.1	0.9	2.9	Ω

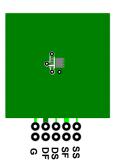
Switching Characteristics

t _{d(on)}	Turn-On Delay Time			8.8	18	ns
t _r	Rise Time	V_{DD} = 13 V, I_{D} = 16.7A, V_{GS} = 10 V, R_{GEN} = 6 Ω		2	10	ns
t _{d(off)}	Turn-Off Delay Time			20	36	ns
t _f	Fall Time			1.6	10	ns
$Q_{g(TOT)}$	Total Gate Charge at 10V			20	28	nC
$Q_{g(TOT)}$	Total Gate Charge at 4.5V	V _{DD} = 13 V, I _D = 16.7 A		9.5	13	nC
Q _{gs}	Total Gate Charge			3.9		nC
Q_{gd}	Gate to Drain "Miller" Charge			2.5		nC

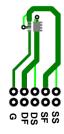
Drain-Source Diode Characteristics

I Source to Drain Diode Forward voltage	Source to Drain Diode, Ferward Voltage	$V_{GS} = 0 \text{ V}, I_S = 16.7 \text{ A}$ (Note 2)		0.8	1.3	V
	$V_{GS} = 0 \text{ V}, I_S = 2 \text{ A}$ (Note 2)		0.7	1.2		
t _{rr}	Reverse Recovery Time	I _E = 16.7 A, di/dt = 100 A/μs		22	39	ns
Q _{rr}	Reverse Recovery Charge	- I _F = 16.7 A, αl/αt = 100 A/μs		7	14	nC

Notes:
1. R_{Q,IA} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{Q,IC} is guaranteed by design while R_{Q,CA} is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 125 °C/W when mounted on a minimum pad of 2 oz copper

^{2.} Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.

^{3.} As an N-ch device, the negative Vgs rating is for low duty cycle pulse ocurrence only. No continuous rating is implied.

^{4.} Eas of 38 mJ is based on starting TJ = 25 oC; N-ch: L = 0.3 mH, Ias = 16 A, VDD = 23 V, VGs = 10 V.

Typical Characteristics T_J = 25°C unless otherwise noted

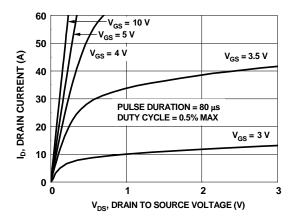


Figure 1. On Region Characteristics

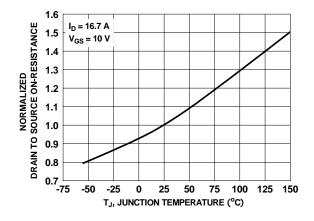


Figure 3. Normalized On Resistance vs Junction Temperature

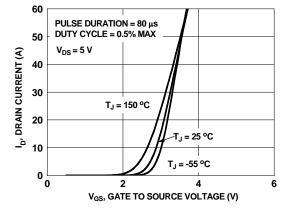


Figure 5. Transfer Characteristics

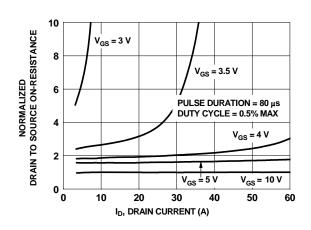


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

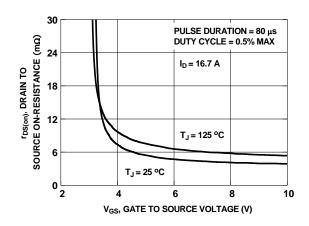


Figure 4. On-Resistance vs Gate to Source Voltage

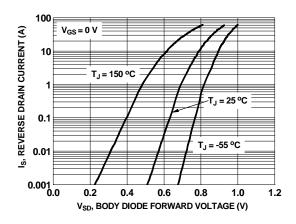


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

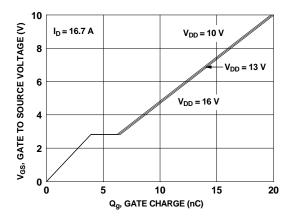


Figure 7. Gate Charge Characteristics

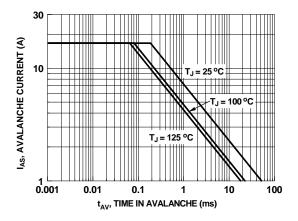


Figure 9. Unclamped Inductive Switching Capability

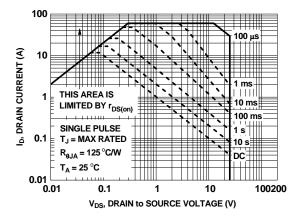


Figure 11. Forward Bias Safe Operating Area

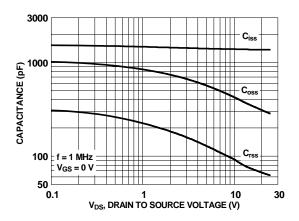


Figure 8. Capacitance vs Drain to Source Voltage

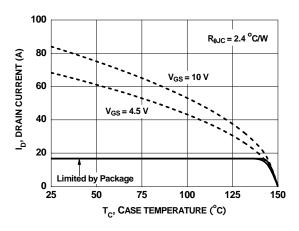


Figure 10. Maximum Continuous Drain Current vs Case Temperature

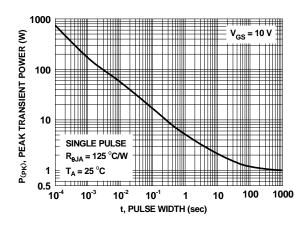


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

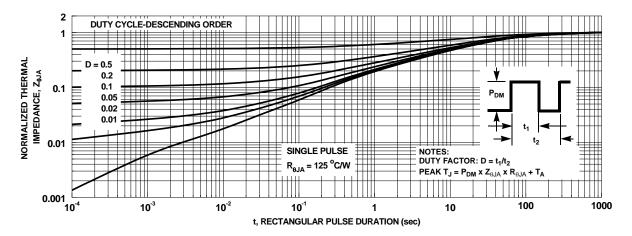
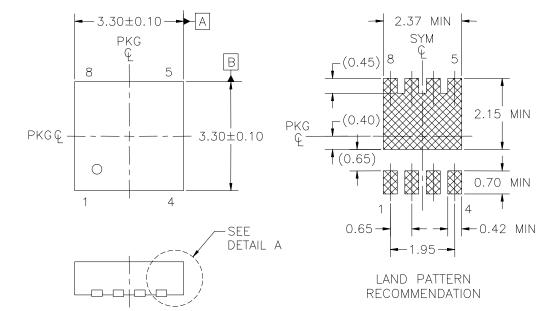
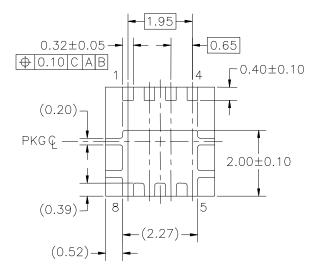
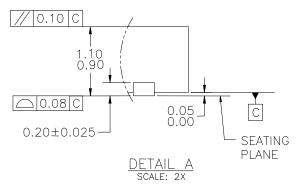


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Dimensional Outline and Pad Layout







NOTES: UNLESS OTHERWISE SPECIFIED

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